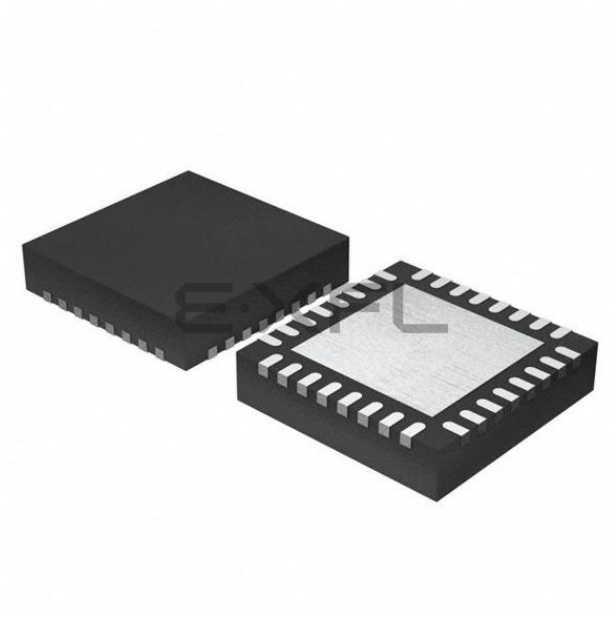


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I²C, Microwire, SmartCard, SPI, SSP, UART/USART, USB
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	26
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	12K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VFQFN Exposed Pad
Supplier Device Package	32-HVQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc11u35fhi33-501

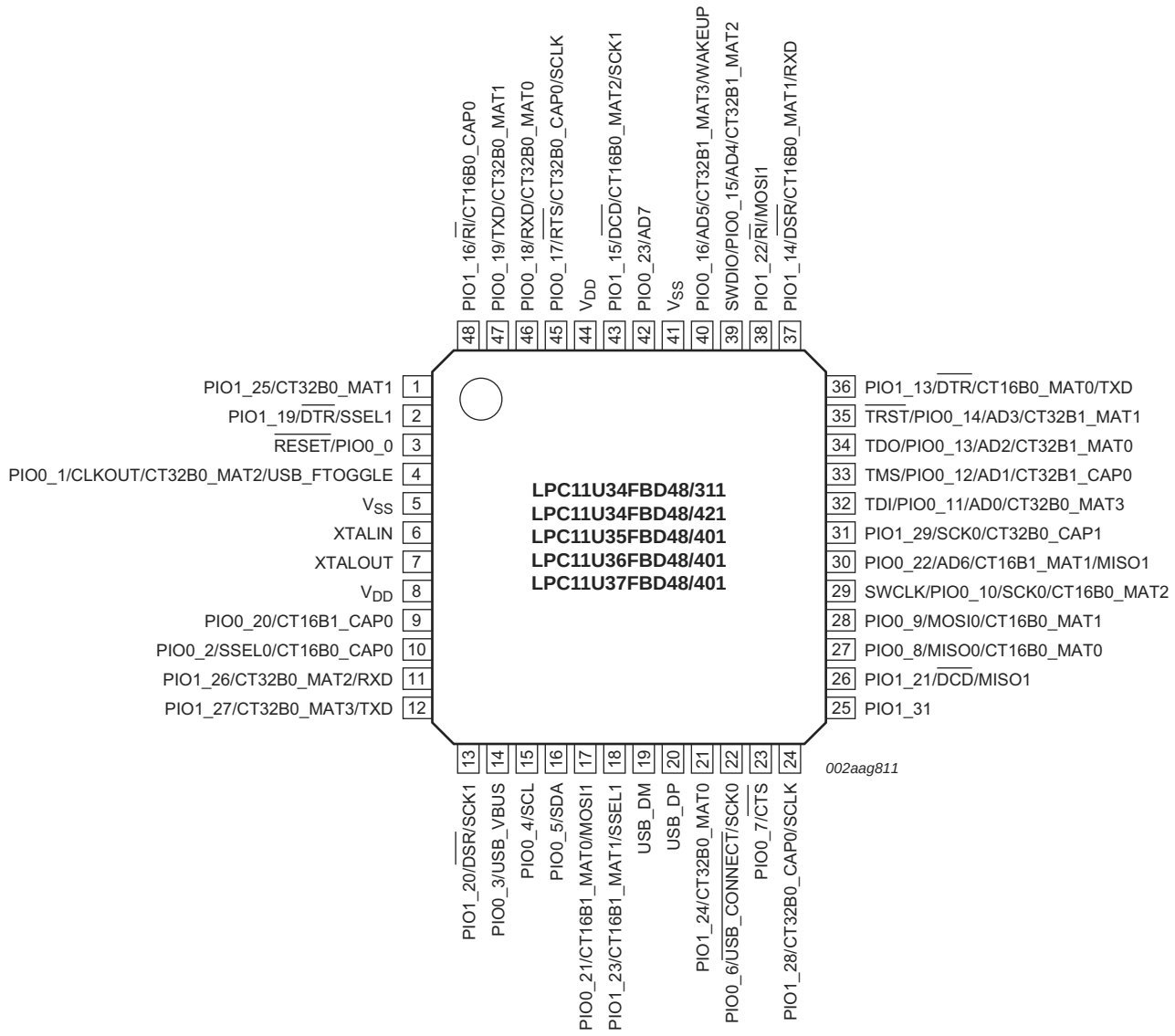


Fig 4. Pin configuration (LQFP48)

Table 3. Pin description

Symbol	Pin HVQFN33	Pin TFBGA48	Pin LQFP48	Pin LQFP64	Reset state [1]	Type	Description
PIO1_16/$\overline{\text{RI}}$/ CT16B0_CAP0	-	A2	48	63 [3]	I; PU	I/O	**PIO1_16 —** General purpose digital input/output pin.
					-	I	**$\overline{\text{RI}}$ —** Ring Indicator input for USART.
					-	I	**CT16B0_CAP0 —** Capture input 0 for 16-bit timer 0.
PIO1_17/CT16B0_CAP1/ RXD	-	-	-	23 [3]	I; PU	I/O	**PIO1_17 —** General purpose digital input/output pin.
					-	I	**CT16B0_CAP1 —** Capture input 1 for 16-bit timer 0.
					-	I	**RXD —** Receiver input for USART.
PIO1_18/CT16B1_CAP1/ TXD	-	-	-	28 [3]	I; PU	I/O	**PIO1_18 —** General purpose digital input/output pin.
					-	I	**CT16B1_CAP1 —** Capture input 1 for 16-bit timer 1.
					-	O	**TXD —** Transmitter output for USART.
PIO1_19/$\overline{\text{DTR}}$/SSEL1	1	B1	2	3 [3]	I; PU	I/O	**PIO1_19 —** General purpose digital input/output pin.
					-	O	**$\overline{\text{DTR}}$ —** Data Terminal Ready output for USART.
					-	I/O	**SSEL1 —** Slave select for SSP1.
PIO1_20/$\overline{\text{DSR}}$/SCK1	-	H1	13	18 [3]	I; PU	I/O	**PIO1_20 —** General purpose digital input/output pin.
					-	I	**$\overline{\text{DSR}}$ —** Data Set Ready input for USART.
					-	I/O	**SCK1 —** Serial clock for SSP1.
PIO1_21/$\overline{\text{DCD}}$/MISO1	-	G8	26	35 [3]	I; PU	I/O	**PIO1_21 —** General purpose digital input/output pin.
					-	I	**$\overline{\text{DCD}}$ —** Data Carrier Detect input for USART.
					-	I/O	**MISO1 —** Master In Slave Out for SSP1.
PIO1_22/$\overline{\text{RI}}$/MOSI1	-	A7	38	51 [3]	I; PU	I/O	**PIO1_22 —** General purpose digital input/output pin.
					-	I	**$\overline{\text{RI}}$ —** Ring Indicator input for USART.
					-	I/O	**MOSI1 —** Master Out Slave In for SSP1.
PIO1_23/CT16B1_MAT1/ SSEL1	-	H4	18	24 [3]	I; PU	I/O	**PIO1_23 —** General purpose digital input/output pin.
					-	O	**CT16B1_MAT1 —** Match output 1 for 16-bit timer 1.
					-	I/O	**SSEL1 —** Slave select for SSP1.
PIO1_24/CT32B0_MAT0	-	G6	21	27 [3]	I; PU	I/O	**PIO1_24 —** General purpose digital input/output pin.
					-	O	**CT32B0_MAT0 —** Match output 0 for 32-bit timer 0.
PIO1_25/CT32B0_MAT1	-	A1	1	2 [3]	I; PU	I/O	**PIO1_25 —** General purpose digital input/output pin.
					-	O	**CT32B0_MAT1 —** Match output 1 for 32-bit timer 0.
PIO1_26/CT32B0_MAT2/ RXD/IOH_19	-	G2	11	14 [3]	I; PU	I/O	**PIO1_26 —** General purpose digital input/output pin.
					-	O	**CT32B0_MAT2 —** Match output 2 for 32-bit timer 0.
					-	I	**RXD —** Receiver input for USART.
					-	I/O	**IOH_19 —** I/O Handler input/output 19. (LPC11U37HFBD64/401 only.)
PIO1_27/CT32B0_MAT3/ TXD/IOH_20	-	G1	12	15 [3]	I; PU	I/O	**PIO1_27 —** General purpose digital input/output pin.
					-	O	**CT32B0_MAT3 —** Match output 3 for 32-bit timer 0.
					-	O	**TXD —** Transmitter output for USART.
					-	I/O	**IOH_20 —** I/O Handler input/output 20. (LPC11U37HFBD64/401 only.)

Table 3. Pin description

Symbol	Pin HVQFN33	Pin TFBGA48	Pin LQFP48	Pin LQFP64	Reset state [1]	Type	Description
PIO1_28/CT32B0_CAP0/ SCLK	-	H7	24	31 [3]	I; PU	I/O	**PIO1_28 —** General purpose digital input/output pin.
					-	I	**CT32B0_CAP0 —** Capture input 0 for 32-bit timer 0.
					-	I/O	**SCLK —** Serial clock input/output for USART in synchronous mode.
PIO1_29/SCK0/ CT32B0_CAP1	-	D7	31	41 [3]	I; PU	I/O	**PIO1_29 —** General purpose digital input/output pin.
					-	I/O	**SCK0 —** Serial clock for SSP0.
					-	I	**CT32B0_CAP1 —** Capture input 1 for 32-bit timer 0.
PIO1_31	-	-	25	- [3]	I; PU	I/O	**PIO1_31 —** General purpose digital input/output pin.
USB_DM	13	G5	19	25 [7]	F	-	**USB_DM —** USB bidirectional D− line.
USB_DP	14	H5	20	26 [7]	F	-	**USB_DP —** USB bidirectional D+ line.
XTALIN	4	D1	6	8 [8]	-	-	Input to the oscillator circuit and internal clock generator circuits. Input voltage must not exceed 1.8 V.
XTALOUT	5	E1	7	9 [8]	-	-	Output from the oscillator amplifier.
V_{DD}	6; 29	B4; E2	8; 44	10; 33; 48; 58	-	-	Supply voltage to the internal regulator, the external rail, and the ADC. Also used as the ADC reference voltage.
V_{SS}	33	B5; D2	5; 41	7; 54	-	-	Ground.

[1] Pin state at reset for default function: I = Input; O = Output; PU = internal pull-up enabled; IA = inactive, no pull-up/down enabled; F = floating; If the pins are not used, tie floating pins to ground or power to minimize power consumption.

[2] 5 V tolerant pad. $\overline{\text{RESET}}$ functionality is not available in Deep power-down mode. Use the WAKEUP pin to reset the chip and wake up from Deep power-down mode. An external pull-up resistor is required on this pin for the Deep power-down mode. See Figure 32 for the reset pad configuration.

[3] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors and configurable hysteresis (see Figure 31).

[4] I^2C-bus pin compliant with the I^2C-bus specification for I^2C standard mode, I^2C Fast-mode, and I^2C Fast-mode Plus. The pin requires an external pull-up to provide output functionality. When power is switched off, this pin is floating and does not disturb the I2C lines. Open-drain configuration applies to all functions on this pin.

[5] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors and configurable hysteresis (see Figure 31); includes high-current output driver.

[6] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors, configurable hysteresis, and analog input. When configured as a ADC input, digital section of the pad is disabled and the pin is not 5 V tolerant (see Figure 31); includes digital input glitch filter.

[7] Pad provides USB functions. It is designed in accordance with the USB specification, revision 2.0 (Full-speed and Low-speed mode only). This pad is not 5 V tolerant.

[8] When the system oscillator is not used, connect XTALIN and XTALOUT as follows: XTALIN can be left floating or can be grounded (grounding is preferred to reduce susceptibility to noise). Leave XTALOUT floating.

application notes from NXP (see http://www.LPCware.com.) LPCXpresso, Keil, and IAR IDEs are supported. I/O Handler library code must be executed from the memory area 0x2000 0000 to 0x2000 07FF. This memory is not available for other use.

For application examples, see Section 11.8 “I/O Handler software library applications”. Each I/O Handler library uses a specific subset of I/O Handler pins and in some cases other pins and peripherals such as the counter/timers.

7.11 USART

The LPC11U3x contains one USART.

The USART includes full modem control, support for synchronous mode, and a smart card interface. The RS-485/9-bit mode allows both software address detection and automatic address detection using 9-bit mode.

The USART uses a fractional baud rate generator. Standard baud rates such as 115200 Bd can be achieved with any crystal frequency above 2 MHz.

7.11.1 Features

- Maximum USART data bit rate of 3.125 Mbit/s.
- 16 byte receive and transmit FIFOs.
- Register locations conform to 16C550 industry standard.
- Receiver FIFO trigger points at 1 B, 4 B, 8 B, and 14 B.
- Built-in fractional baud rate generator covering wide range of baud rates without a need for external crystals of particular values.
- Fractional divider for baud rate control, auto baud capabilities and FIFO control mechanism that enables software flow control implementation.
- Support for RS-485/9-bit mode.
- Support for modem control.
- Support for synchronous mode.
- Includes smart card interface.

7.12 SSP serial I/O controller

The SSP controllers operate on a SSP, 4-wire SSI, or Microwire bus. The controller can interact with multiple masters and slaves on the bus. Only a single master and a single slave can communicate on the bus during a given data transfer. The SSP supports full duplex transfers, with frames of 4 bit to 16 bit of data flowing from the master to the slave and from the slave to the master. In practice, often only one of these data flows carries meaningful data.

7.12.1 Features

- Maximum SSP speed of 25 Mbit/s (master) or 4.17 Mbit/s (slave) (in SSP mode)
- Compatible with Motorola SPI (Serial Peripheral Interface), 4-wire Texas Instruments SSI (Serial Synchronous Interface), and National Semiconductor Microwire buses
- Synchronous serial communication
- Master or slave operation

- 8-frame FIFOs for both transmit and receive
- 4-bit to 16-bit frame

7.13 I²C-bus serial I/O controller

The LPC11U3x contain one I²C-bus controller.

The I²C-bus is bidirectional for inter-IC control using only two wires: a Serial CLock line (SCL) and a Serial DAta line (SDA). Each device is recognized by a unique address and can operate as either a receiver-only device (e.g., an LCD driver) or a transmitter with the capability to both receive and send information (such as memory). Transmitters and/or receivers can operate in either master or slave mode, depending on whether the chip has to initiate a data transfer or is only addressed. The I²C-bus is a multi-master bus, and more than one bus master connected to the interface can be controlled the bus.

7.13.1 Features

- The I²C-interface is an I²C-bus compliant interface with open-drain pins. The I²C-bus interface supports Fast-mode Plus with bit rates up to 1 Mbit/s.
- Easy to configure as master, slave, or master/slave.
- Programmable clocks allow versatile rate control.
- Bidirectional data transfer between masters and slaves.
- Multi-master bus (no central master).
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus.
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- The I²C-bus can be used for test and diagnostic purposes.
- The I²C-bus controller supports multiple address recognition and a bus monitor mode.

7.14 10-bit ADC

The LPC11U3x contains one ADC. It is a single 10-bit successive approximation ADC with eight channels.

7.14.1 Features

- 10-bit successive approximation ADC.
- Input multiplexing among 8 pins.
- Power-down mode.
- Measurement range 0 V to V_{DD}.
- 10-bit conversion time $\geq$ 2.44 μs (up to 400 kSamples/s).
- Burst conversion mode for single or multiple inputs.
- Optional conversion on transition of input pin or timer match signal.
- Individual result registers for each ADC channel to reduce interrupt overhead.

7.15 General purpose external event counter/timers

The LPC11U3x includes two 32-bit counter/timers and two 16-bit counter/timers. The counter/timer is designed to count cycles of the system derived clock. It can optionally generate interrupts or perform other actions at specified timer values, based on four match registers. Each counter/timer also includes one capture input to trap the timer value when an input signal transitions, optionally generating an interrupt.

7.15.1 Features

- A 32-bit/16-bit timer/counter with a programmable 32-bit/16-bit prescaler.
- Counter or timer operation.
- Up to two capture channels per timer, that can take a snapshot of the timer value when an input signal transitions. A capture event can also generate an interrupt.
- Four match registers per timer that allow:
  - Continuous operation with optional interrupt generation on match.
  - Stop timer on match with optional interrupt generation.
  - Reset timer on match with optional interrupt generation.
- Up to four external outputs corresponding to match registers, with the following capabilities:
  - Set LOW on match.
  - Set HIGH on match.
  - Toggle on match.
  - Do nothing on match.
- The timer and prescaler can be configured to be cleared on a designated capture event. This feature permits easy pulse-width measurement by clearing the timer on the leading edge of an input pulse and capturing the timer value on the trailing edge.

7.16 System tick timer

The ARM Cortex-M0 includes a system tick timer (SYSTICK) that is intended to generate a dedicated SYSTICK exception at a fixed time interval (typically 10 ms).

7.17 Windowed WatchDog Timer (WWDT)

The purpose of the WWDT is to prevent an unresponsive system state. If software fails to update the watchdog within a programmable time window, the watchdog resets the microcontroller

7.17.1 Features

- Internally resets chip if not periodically reloaded during the programmable time-out period.
- Optional windowed operation requires reload to occur between a minimum and maximum time period, both programmable.
- Optional warning interrupt can be generated at a programmable time before watchdog time-out.

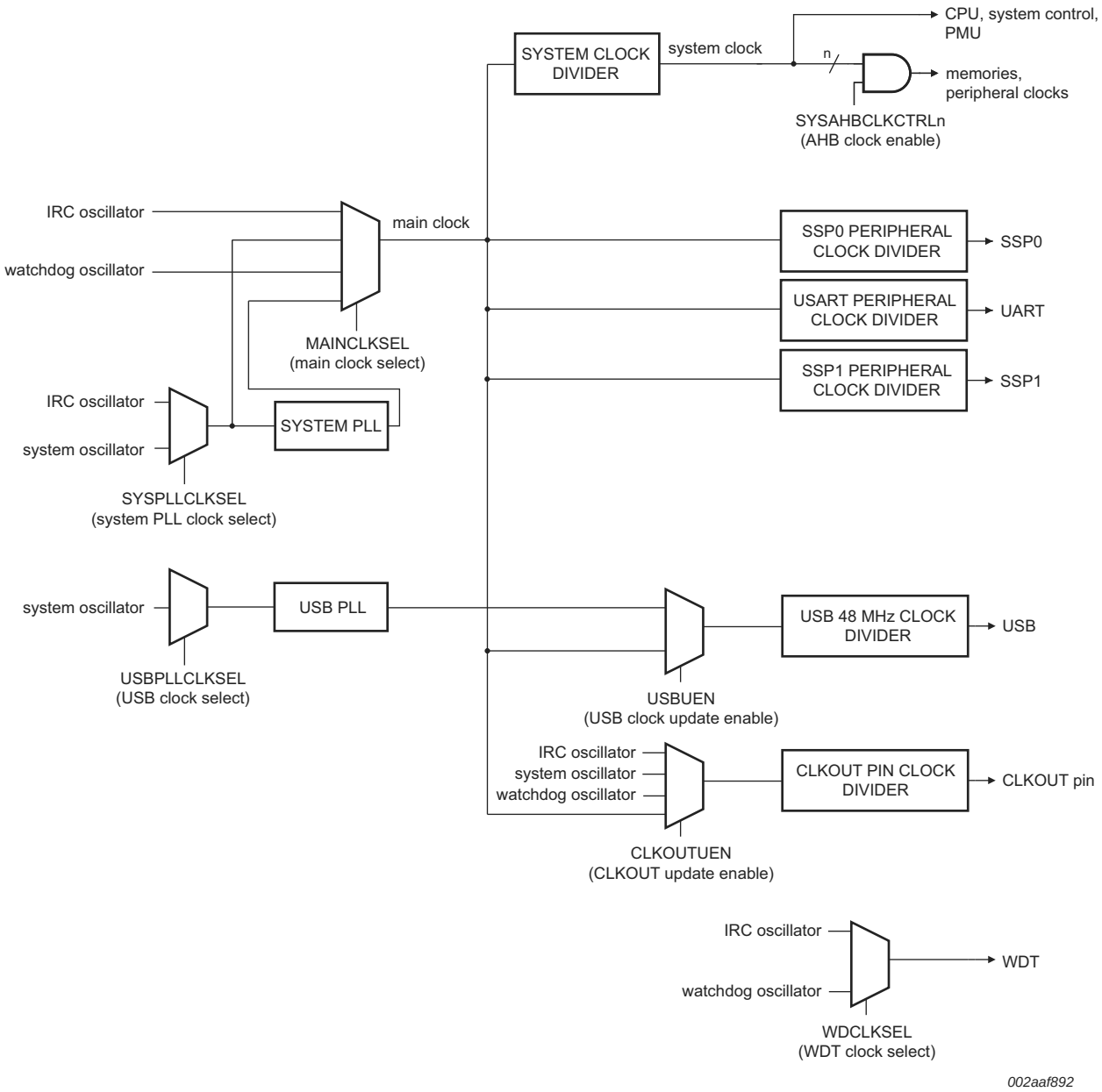


Fig 7. LPC11U3x clocking generation block diagram

7.18.1.1 Internal RC oscillator

The IRC can be used as the clock source for the WDT, and/or as the clock that drives the system PLL and then the CPU. The nominal IRC frequency is 12 MHz.

Upon power-up, any chip reset, or wake-up from Deep power-down mode, the LPC11U3x use the IRC as the clock source. Software can later switch to one of the other available clock sources.

7.18.1.2 System oscillator

The system oscillator can be used as the clock source for the CPU, with or without using the PLL. On the LPC11U3x, use the system oscillator to provide the clock source to USB.

The system oscillator operates at frequencies of 1 MHz to 25 MHz. This frequency can be boosted to a higher frequency, up to the maximum CPU operating frequency, by the system PLL.

7.18.1.3 Watchdog oscillator

The watchdog oscillator can be used as a clock source that directly drives the CPU, the watchdog timer, or the CLKOUT pin. The watchdog oscillator nominal frequency is programmable between 9.4 kHz and 2.3 MHz. The frequency spread over processing and temperature is ±40 % (see also Table 13).

7.18.2 System PLL and USB PLL

The LPC11U3x contain a system PLL and a dedicated PLL for generating the 48 MHz USB clock. The system and USB PLLs are identical.

The PLL accepts an input clock frequency in the range of 10 MHz to 25 MHz. The input frequency is multiplied up to a high frequency with a Current Controlled Oscillator (CCO). The multiplier can be an integer value from 1 to 32. The CCO operates in the range of 156 MHz to 320 MHz. To support this frequency range, an additional divider keeps the CCO within its frequency range while the PLL is providing the desired output frequency. The output divider can be set to divide by 2, 4, 8, or 16 to produce the output clock. The PLL output frequency must be lower than 100 MHz. Since the minimum output divider value is 2, it is insured that the PLL output has a 50 % duty cycle. The PLL is turned off and bypassed following a chip reset. Software can enable the PLL later. The program must configure and activate the PLL, wait for the PLL to lock, and then connect to the PLL as a clock source. The PLL settling time is 100 μs.

7.18.3 Clock output

The LPC11U3x feature a clock output function that routes the IRC oscillator, the system oscillator, the watchdog oscillator, or the main clock to an output pin.

7.18.4 Wake-up process

The LPC11U3x begin operation by using the 12 MHz IRC oscillator as the clock source at power-up and when awakened from Deep power-down mode . This mechanism allows chip operation to resume quickly. If the application uses the main oscillator or the PLL, software must enable these components and wait for them to stabilize. Only then can the system use the PLL and main oscillator as a clock source.

7.18.5 Power control

The LPC11U3x support various power control features. There are four special modes of processor power reduction: Sleep mode, Deep-sleep mode, Power-down mode, and Deep power-down mode. The CPU clock rate can also be controlled as needed by changing clock sources, reconfiguring PLL values, and/or altering the CPU clock divider value. This power control mechanism allows a trade-off of power versus processing speed based on application requirements. In addition, a register is provided for shutting down the clocks to individual on-chip peripherals. This register allows fine-tuning of power

Power-down mode reduces power consumption compared to Deep-sleep mode at the expense of longer wake-up times.

7.18.5.5 Deep power-down mode

In Deep power-down mode, power is shut off to the entire chip except for the WAKEUP pin. The LPC11U3x can wake up from Deep power-down mode via the WAKEUP pin.

The LPC11U3x can be prevented from entering Deep power-down mode by setting a lock bit in the PMU block. Locking out Deep power-down mode enables the application to keep the watchdog timer or the BOD running at all times.

When entering Deep power-down mode, an external pull-up resistor is required on the WAKEUP pin to hold it HIGH. Pull the $\overline{\text{RESET}}$ pin HIGH to prevent it from floating while in Deep power-down mode.

7.18.6 System control

7.18.6.1 Reset

Reset has four sources on the LPC11U3x: the $\overline{\text{RESET}}$ pin, the Watchdog reset, power-on reset (POR), and the BrownOut Detection (BOD) circuit. The $\overline{\text{RESET}}$ pin is a Schmitt trigger input pin. Assertion of chip reset by any source, once the operating voltage attains a usable level, starts the IRC and initializes the flash controller.

A LOW-going pulse as short as 50 ns resets the part.

When the internal Reset is removed, the processor begins executing at address 0, which is initially the Reset vector mapped from the boot block. At that point, all of the processor and peripheral registers have been initialized to predetermined values.

In Deep power-down mode, an external pull-up resistor is required on the $\overline{\text{RESET}}$ pin.

7.18.6.2 Brownout detection

The LPC11U3x includes up to four levels for monitoring the voltage on the V_{DD} pin. If this voltage falls below one of the selected levels, the BOD asserts an interrupt signal to the NVIC. This signal can be enabled for interrupt in the Interrupt Enable Register in the NVIC to cause a CPU interrupt. Alternatively, software can monitor the signal by reading a dedicated status register. Four threshold levels can be selected to cause a forced reset of the chip.

7.18.6.3 Code security (Code Read Protection - CRP)

CRP provides different levels of security in the system so that access to the on-chip flash and use of the Serial Wire Debugger (SWD) and In-System Programming (ISP) can be restricted. Programming a specific pattern into a dedicated flash location invokes CRP. IAP commands are not affected by the CRP.

In addition, ISP entry via the PIO0_1 pin can be disabled without enabling CRP. For details, see the *LPC11Uxx user manual*.

There are three levels of Code Read Protection:

9. Static characteristics

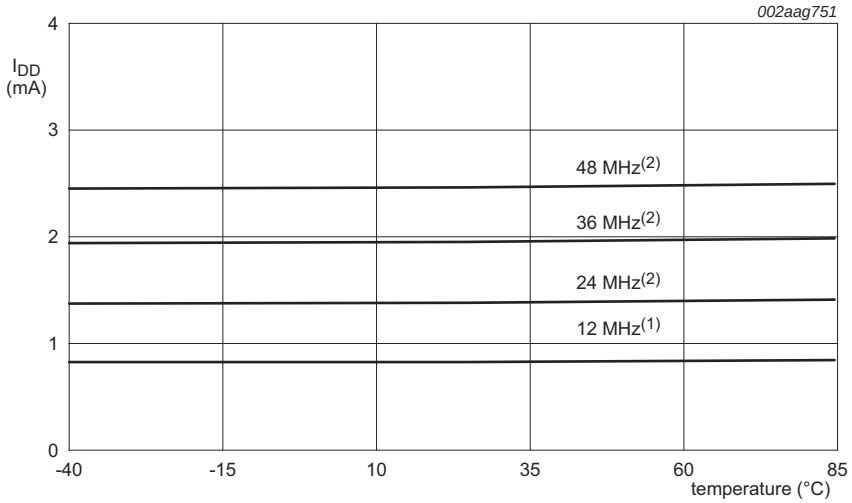
Table 5. Static characteristics

T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
V_{DD}	supply voltage (core and external rail)	[2]	1.8	3.3	3.6	V
I_{DD}	supply current	Active mode; V_{DD} = 3.3 V; T_{amb} = 25 °C; code `while(1){}` executed from flash;				
		system clock = 12 MHz [3][4][5][6][7][8]	-	2	-	mA
		system clock = 50 MHz [4][5][6][7][8][9]	-	7	-	mA
		Sleep mode; V_{DD} = 3.3 V; T_{amb} = 25 °C; system clock = 12 MHz [3][4][5][6][7][8]	-	1	-	mA
		Deep-sleep mode; V_{DD} = 3.3 V; T_{amb} = 25 °C [4][7]	-	300	-	μA
		Power-down mode; V_{DD} = 3.3 V; T_{amb} = 25 °C	-	2	-	μA
		Deep power-down mode; V_{DD} = 3.3 V; T_{amb} = 25 °C [10]	-	220	-	nA
Standard port pins, $\overline{\text{RESET}}$						
I_{IL}	LOW-level input current	V_I = 0 V; on-chip pull-up resistor disabled	-	0.5	10	nA
I_{IH}	HIGH-level input current	V_I = V_{DD}; on-chip pull-down resistor disabled	-	0.5	10	nA
I_{OZ}	OFF-state output current	V_O = 0 V; V_O = V_{DD}; on-chip pull-up/down resistors disabled	-	0.5	10	nA
V_I	input voltage	pin configured to provide a digital function; $V_{DD} \geq 1.8$ V [11][12]	0	-	5.0	V
		V_{DD} = 0 V	0	-	3.6	V
V_O	output voltage	output active	0	-	V_{DD}	V
V_{IH}	HIGH-level input voltage		$0.7V_{DD}$	-	-	V
V_{IL}	LOW-level input voltage		-	-	$0.3V_{DD}$	V
V_{hys}	hysteresis voltage		-	0.4	-	V
V_{OH}	HIGH-level output voltage	2.0 V ≤ V_{DD} ≤ 3.6 V; I_{OH} = −4 mA	V_{DD} − 0.4	-	-	V
		1.8 V ≤ V_{DD} < 2.0 V; I_{OH} = −3 mA	V_{DD} − 0.4	-	-	V
V_{OL}	LOW-level output voltage	2.0 V ≤ V_{DD} ≤ 3.6 V; I_{OL} = 4 mA	-	-	0.4	V
		1.8 V ≤ V_{DD} < 2.0 V; I_{OL} = 3 mA	-	-	0.4	V
I_{OH}	HIGH-level output current	V_{OH} = V_{DD} − 0.4 V; 2.0 V ≤ V_{DD} ≤ 3.6 V	−4	-	-	mA
		1.8 V ≤ V_{DD} < 2.0 V	−3	-	-	mA

Table 5. Static characteristics *…continued*
T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
I_{OL}	LOW-level output current	V_{OL} = 0.4 V 2.0 V ≤ V_{DD} ≤ 3.6 V	4	-	-	mA
		1.8 V ≤ V_{DD} < 2.0 V	3	-	-	mA
I_{OHS}	HIGH-level short-circuit output current	V_{OH} = 0 V [13]	-	-	−45	mA
I_{OLS}	LOW-level short-circuit output current	V_{OL} = V_{DD} [13]	-	-	50	mA
I_{pd}	pull-down current	V_I = 5 V	10	50	150	μA
I_{pu}	pull-up current	V_I = 0 V; 2.0 V ≤ V_{DD} ≤ 3.6 V	−15	−50	−85	μA
		1.8 V ≤ V_{DD} < 2.0 V	−10	−50	−85	μA
		V_{DD} < V_I < 5 V	0	0	0	μA
High-drive output pin (PIO0_7)						
I_{IL}	LOW-level input current	V_I = 0 V; on-chip pull-up resistor disabled	-	0.5	10	nA
I_{IH}	HIGH-level input current	V_I = V_{DD}; on-chip pull-down resistor disabled	-	0.5	10	nA
I_{OZ}	OFF-state output current	V_O = 0 V; V_O = V_{DD}; on-chip pull-up/down resistors disabled	-	0.5	10	nA
V_I	input voltage	pin configured to provide a digital function; V_{DD} ≥ 1.8 V [11] [12]	0	-	5.0	V
		V_{DD} = 0 V	0	-	3.6	V
V_O	output voltage	output active	0	-	V_{DD}	V
V_{IH}	HIGH-level input voltage		0.7V_{DD}	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.3V_{DD}	V
V_{hys}	hysteresis voltage		0.4	-	-	V
V_{OH}	HIGH-level output voltage	2.5 V ≤ V_{DD} ≤ 3.6 V; I_{OH} = −20 mA	V_{DD} − 0.4	-	-	V
		1.8 V ≤ V_{DD} < 2.5 V; I_{OH} = −12 mA	V_{DD} − 0.4	-	-	V
V_{OL}	LOW-level output voltage	2.0 V ≤ V_{DD} ≤ 3.6 V; I_{OL} = 4 mA	-	-	0.4	V
		1.8 V ≤ V_{DD} < 2.0 V; I_{OL} = 3 mA	-	-	0.4	V
I_{OH}	HIGH-level output current	V_{OH} = V_{DD} − 0.4 V; 2.5 V ≤ V_{DD} ≤ 3.6 V	20	-	-	mA
		1.8 V ≤ V_{DD} < 2.5 V	12	-	-	mA
I_{OL}	LOW-level output current	V_{OL} = 0.4 V 2.0 V ≤ V_{DD} ≤ 3.6 V	4	-	-	mA
		1.8 V ≤ V_{DD} < 2.0 V	3	-	-	mA
I_{OLS}	LOW-level short-circuit output current	V_{OL} = V_{DD} [13]	-	-	50	mA
I_{pd}	pull-down current	V_I = 5 V	10	50	150	μA

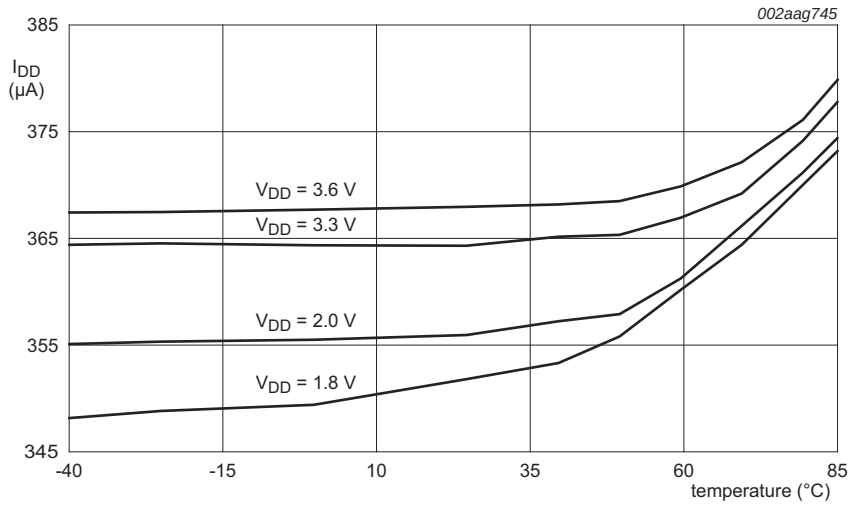


Conditions: V_{DD} = 3.3 V; Sleep mode entered from flash; internal pull-up resistors disabled; BOD disabled; all peripherals disabled in the SYSAHBCLKCTRL register; all peripheral clocks disabled; low-current mode; USB_DP and USB_DM pulled LOW externally.

(1) System oscillator and system PLL disabled; IRC enabled.

(2) System oscillator and system PLL enabled; IRC disabled.

Fig 11. Typical supply current versus temperature in Sleep mode



Conditions: BOD disabled; all oscillators and analog blocks turned off in the PDSLEEPCFG register; USB_DP and USB_DM pulled LOW externally.

Fig 12. Typical supply current versus temperature in Deep-sleep mode

Table 8. Power consumption for individual analog and digital blocks

Peripheral	Typical supply current in mA			Notes
	n/a	12 MHz	48 MHz	
IRC	0.27	-	-	System oscillator running; PLL off; independent of main clock frequency.
System oscillator at 12 MHz	0.22	-	-	IRC running; PLL off; independent of main clock frequency.
Watchdog oscillator at 500 kHz/2	0.004	-	-	System oscillator running; PLL off; independent of main clock frequency.
BOD	0.051	-	-	Independent of main clock frequency.
Main PLL	-	0.21	-	-
ADC	-	0.08	0.29	-
CLKOUT	-	0.12	0.47	Main clock divided by 4 in the CLKOUTDIV register.
CT16B0	-	0.02	0.06	-
CT16B1	-	0.02	0.06	-
CT32B0	-	0.02	0.07	-
CT32B1	-	0.02	0.06	-
GPIO	-	0.23	0.88	GPIO pins configured as outputs and set to LOW. Direction and pin state are maintained if the GPIO is disabled in the SYSAHBCLKCFG register.
IOCONFIG	-	0.03	0.10	-
I^2C	-	0.04	0.13	-
ROM	-	0.04	0.15	-
SPI0	-	0.12	0.45	-
SPI1	-	0.12	0.45	-
UART	-	0.22	0.82	-
WWDT	-	0.02	0.06	Main clock selected as clock source for the WDT.
USB	-	-	1.2	-

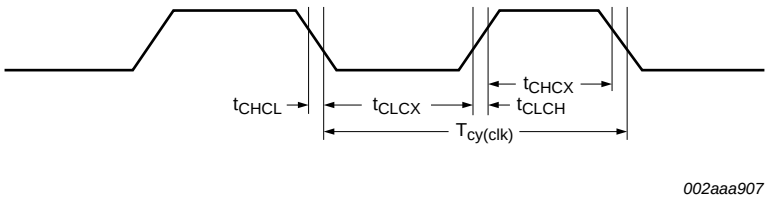


Fig 21. External clock timing (with an amplitude of at least $V_{i(RMS)}$ = 200 mV)

10.3 Internal oscillators

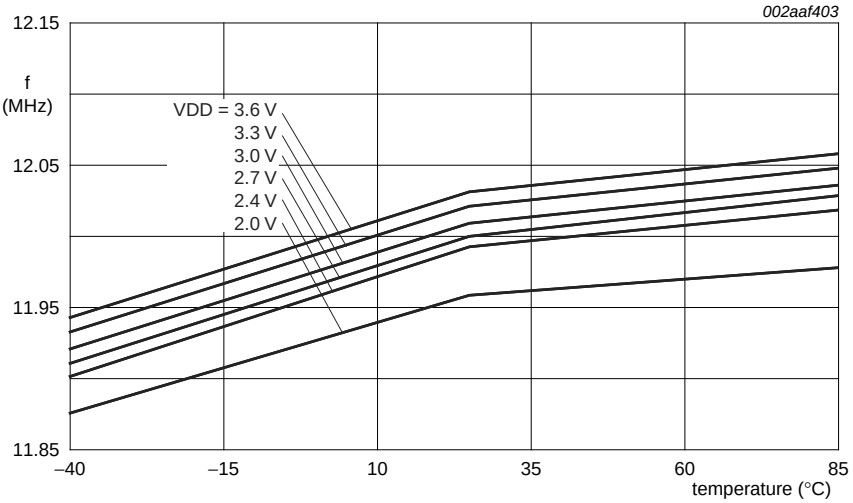
Table 12. Dynamic characteristics: IRC

T_{amb} = −40 °C to +85 °C; 2.7 V ≤ V_{DD} ≤ 3.6 V[1].

Symbol	Parameter	Conditions	Min	Typ[2]	Max	Unit
$f_{osc(RC)}$	internal RC oscillator frequency	-	11.88	12	12.12	MHz

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.



Conditions: Frequency values are typical values. 12 MHz ± 1 % accuracy is guaranteed for 2.7 V ≤ V_{DD} ≤ 3.6 V and T_{amb} = −40 °C to +85 °C. Variations between parts may cause the IRC to fall outside the 12 MHz ± 1 % accuracy specification for voltages below 2.7 V.

Fig 22. Internal RC oscillator frequency versus temperature

Table 13. Dynamic characteristics: Watchdog oscillator

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
$f_{osc(int)}$	internal oscillator frequency	DIVSEL = 0x1F, FREQSEL = 0x1 in the WDTOSCCTRL register; [2][3]	-	9.4	-	kHz
		DIVSEL = 0x00, FREQSEL = 0xF in the WDTOSCCTRL register [2][3]	-	2300	-	kHz

[1] Typical ratings are not guaranteed. The values listed are at nominal supply voltages.

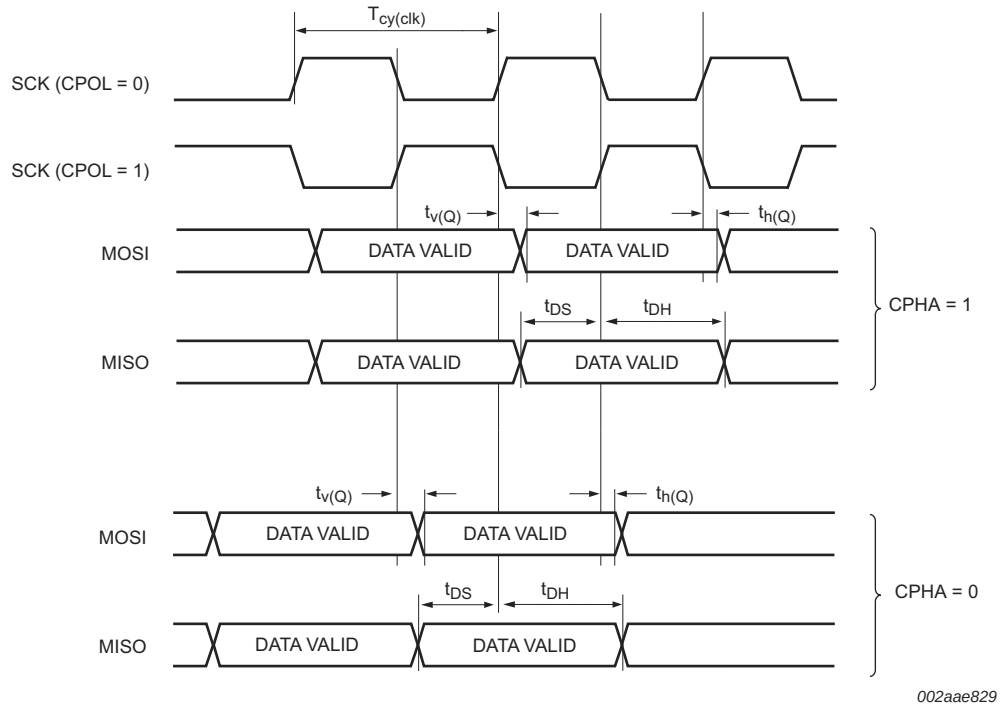


Fig 24. SSP master timing in SPI mode

11.4 Standard I/O pad configuration

Figure 31 shows the possible pin modes for standard I/O pins with analog input function:

- Digital output driver
- Digital input: Pull-up enabled/disabled
- Digital input: Pull-down enabled/disabled
- Digital input: Repeater mode enabled/disabled
- Analog input

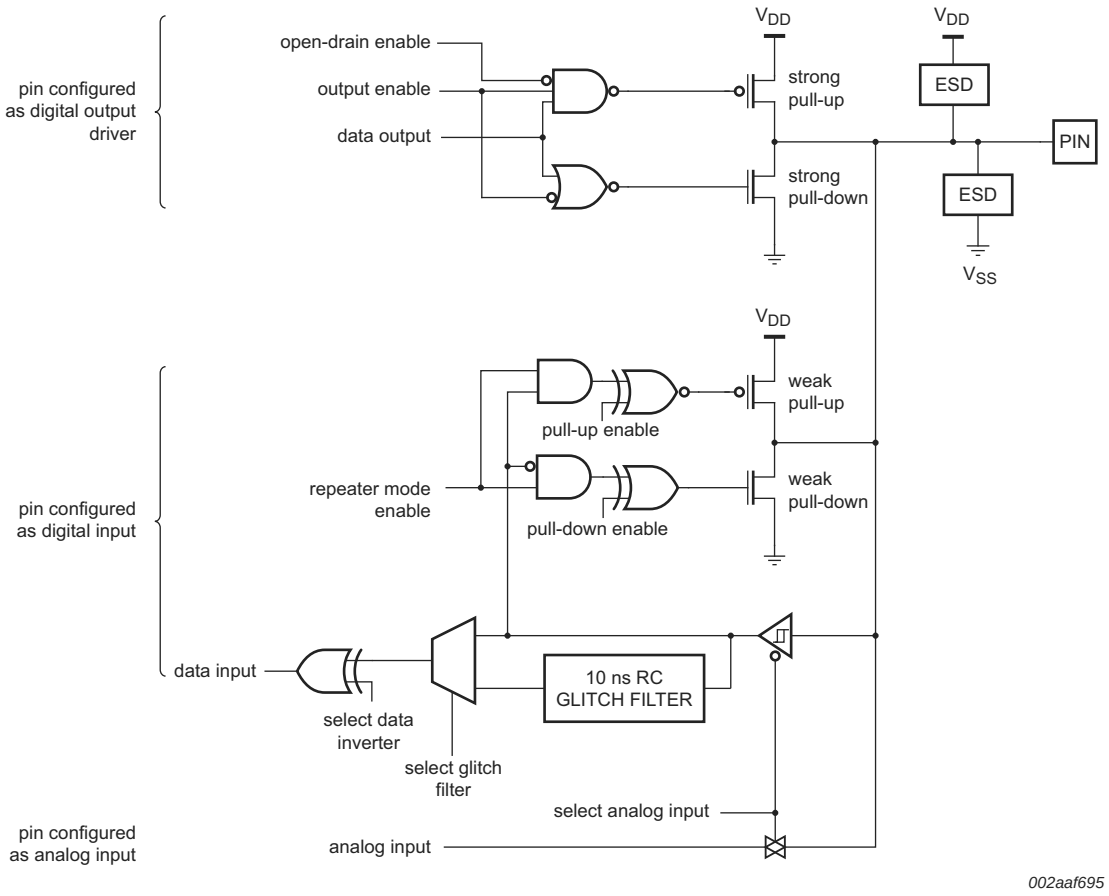
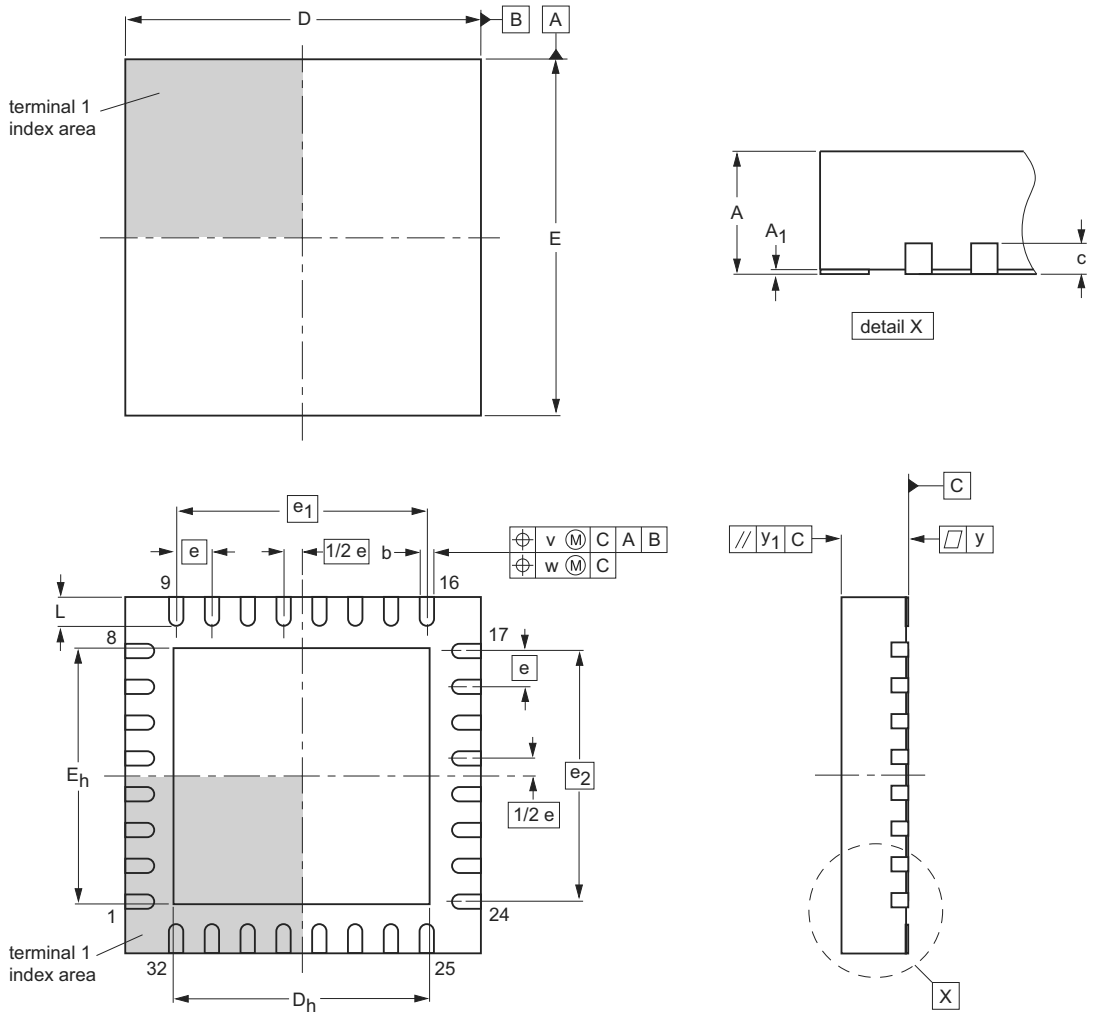


Fig 31. Standard I/O pad configuration

12. Package outline

HVQFN33: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.85 mm



Dimensions (mm are the original dimensions)

Unit[1]		A[1]	A_1	b	c	D[1]	D_h	E[1]	E_h	e	e_1	e_2	L	v	w	y	y_1
mm	max	0.85	0.05	0.30	0.2	5.1	3.75	5.1	3.75	0.5	3.5	3.5	0.5	0.1	0.05	0.05	0.1
	nom																
	min		0.00	0.18		4.9	3.45	4.9	3.45				0.3				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

hvqfn33f_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
		MO-220				~~11-10-11~~ 11-10-17

Fig 34. Package outline HVQFN33 (5 x 5 x 0.85 mm)

14. Abbreviations

Table 20. Abbreviations

Acronym	Description
A/D	Analog-to-Digital
ADC	Analog-to-Digital Converter
AHB	Advanced High-performance Bus
APB	Advanced Peripheral Bus
BOD	BrownOut Detection
GPIO	General Purpose Input/Output
JTAG	Joint Test Action Group
PLL	Phase-Locked Loop
RC	Resistor-Capacitor
SPI	Serial Peripheral Interface
SSI	Serial Synchronous Interface
SSP	Synchronous Serial Port
TAP	Test Access Port
USART	Universal Synchronous Asynchronous Receiver/Transmitter

15. References

[1] LPC11U3x User manual UM10462:
http://www.nxp.com/documents/user_manual/UM10462.pdf

[2] LPC11U3x Errata sheet:
http://www.nxp.com/documents/errata_sheet/ES_LPC11U3X.pdf

16. Revision history

Table 21. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
LPC11U3X v.2.3	20170208	Product data sheet	-	LPC11U3X v.2.2
Modifications:	• Updated Section 1 “General description”: Software libraries for multiple I/O Handler applications are available on nxp.com.			
LPC11U3X v.2.2	20140311	Product data sheet	-	LPC11U3X v.2.1
Modifications:	• Use of USB_CONNECT signal explained in Section 11.1 “Suggested USB interface solutions”. • Open-drain I^2C-bus and $\overline{\text{RESET}}$ pin descriptions clarified. See Table 3.			
LPC11U3X v.2.1	20131230	Product data sheet	-	LPC11U3X v.2
Modifications:		Add reserved function to pins PIO0_8/MISO0/CT16B0_MAT0/R/IOH_6 and PIO0_9/MOSI0/CT16B0_MAT1/R/IOH_7.		
LPC11U3X v.2	20131125	Product data sheet	-	LPC11U3X v.1.1
Modifications:		• Part LPC11U37HFBD64/401 with I/O handler added. • Additional I/O Handler pin functions added in Table 3. • Typical range of watchdog oscillator frequency changed to 9.4 kHz to 2.3 MHz.See Table 13. • Section 11.8 “I/O Handler software library applications” added. • Updated Section 11.1 “Suggested USB interface solutions” for clarity. • Condition V_{DD} = 0 V added to Parameter V_I in Table 5 for clarity.		
LPC11U3X v.1.1	20130924	Product data sheet	-	LPC11U3X v.1
Modifications:		• Removed the footnote “The peak current is limited to 25 times the corresponding maximum current.” in Table 4. • Table 3: Added “5 V tolerant pad” to $\overline{\text{RESET}}$/PIO0_0 table note. • Table 7: Removed BOD interrupt level 0. • Programmable glitch filter is enabled by default. See Section 7.7.1. • Added Section 11.6 “ADC effective input impedance”. • Table 5 “Static characteristics” added Pin capacitance section. • Updated Section 11.1 “Suggested USB interface solutions”. • Table 4 “Limiting values”: – Updated V_{DD} min and max. – Updated V_I conditions. • Table 10 “EEPROM characteristics”: – Removed f_{clk} and t_{er}; the user does not have control over these parameters. – Changed the t_{prog} from 1.1 ms to 2.9 ms; the EEPROM IAP always does an erase and program, thus the total program time is $t_{er} + t_{prog}$. • Changed title of Figure 29 from “USB interface on a self-powered device” to “USB interface with soft-connect”. • Section 10.7 “USB interface” added. Parameter t_{EOPR1} and t_{EOPR2} renamed to t_{EOPR}.		
LPC11U3X v.1	20120420	Product data sheet	-	-

19. Contents

continued >>